**Technical offer**

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| --- | --- | --- | --- |
| Name of Vendor: | [Insert Name of Vendor] | Date: |  |
| ITB reference: | RFP/OLWS/04/2022 | | |

The proposal should be organized to follow this format of the Technical offer, the vendor must describe the exact type with technical characteristics of each item. The quality of the materials may exceed the minimal technical requirements of this RFP

Where a descriptive response is requested, failure to provide the same will be viewed as non-responsive.

| No | Offered description of the items with print | Quantity | Visualization |
| --- | --- | --- | --- |
|  | **Motherboard**  Memory:  Expansion:  Multi-GPU Support:  Storage:  USB:  Audio:  Back Panel I/O Ports:  Internal I/O Connectors:  Special Features:  BIOS:  Manageability:  Accessories: | 1 |  |
|  | **Processor**  General Specifications:  Connectivity:  Key Features: | 1 |  |
|  | **RAM**  Description: | 2 |  |
|  | **HDD**  Description: | 6 |  |
|  | **Video card**  GPU Engine Specs:  Memory Specs:  Technology Support:  Display Support:  Card Dimensions:  Thermal and Power Specs: | 1 |  |
|  | **SSD**  Description: | 2 |  |
|  | **BOX**  Description: | 1 |  |
|  | **POWER SUPPLY**  Description: | 1 |  |
|  | **OS**  Description: | 1 |  |
|  | **Optical mouse**  Description: | 1 |  |
|  | **Keyboard**  Description: | 1 |  |

|  |  |
| --- | --- |
| Delivery time | [In working days] |

We declare that the assembling of the described items and transportation of the final product will be at our expense.

We attach the following:

1. …………………(any other information regarding the Technical offer)